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Ventec International Group to highlight glass-free and high-performance materials for advanced PCBs at electronica 2026

See Ventec at Booth 207, Hall A1, Electronica 2026, November 10-13

- Meet Ventec's materials specialists and automation experts at Booth 207, Hall A1
- Discover solutions to PCB design and manufacturing challenges

At electronica 2026, Ventec International Group will present advanced material solutions for designers working at the boundaries of high-speed signal integrity, thermal management and physical space constraints. Experts from Ventec Giga will also be available to discuss PCB manufacturing equipment, factory planning and long-term manufacturing support.

At Hall A1, Booth 207, Ventec's materials specialists will showcase the latest glass-free pro-bond and thermal-bond materials, highlighting how they can help reduce board thickness while delivering predictable performance and effective thermal management.

The team will also showcase ultra-low-loss prepregs and laminates for designers facing tight noise budgets in RF and microwave applications. Ventec's tec-speed 30.0, with a dissipation factor (Df) as low as 0.00035 at 10 GHz, and tec-speed 20.0, with a Df of 0.0023 and a dielectric constant (Dk) of up to 10.2, offer material solutions for demanding high-frequency designs, helping minimise signal loss and preserve signal-to-noise ratio (SNR).

In addition, Ventec will highlight its FR4.1 and FR15.1 halogen free material ranges, which offer enhanced thermal and mechanical stability compared with conventional FR4 materials, alongside improved conductive anodic filament (CAF) resistance for demanding operating environments. The booth will also feature Ventec's polyimide materials for applications requiring high reliability at elevated ambient temperatures.

Further highlights in Munich will include Ventec's distribution portfolio, featuring ThinFlex adhesive-less, single- and double-sided flexible copper-clad laminates (FCCLs) and coverlays. Designed to support high-performance assemblies in compact or space-constrained applications, ThinFlex materials offer excellent reliability, fine-line etching capability, low moisture absorption and dimensional stability.

Ventec also distributes a broad range of products for PCB manufacturers, with solutions from leading brands featured at electronica. Visitors can explore how copper foils, thermal interface materials, drilling products, lamination accessories, press plates, and precision drills and routers can support PCB fabrication and help meet demanding production requirements.

Meet Ventec at electronica 2026
electronica 2026 takes place at Messe München, Munich, Germany, from 10–13 November 2026.
Visit Ventec at Booth 207, Hall A1 to meet the team and explore solutions for your next PCB design or manufacturing challenge.

The Ventec team looks forward to welcoming you!

Further information about Ventec's solutions and the company's wide variety of products is available at www.venteclaminates.com

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Available images



Image source: Ventec International Group

About Ventec International Group

Ventec International Group Co., Ltd. is a Taiwan Stock Exchange listed (TWSE:6672.TT) global supplier of advanced base materials for the PCB industry worldwide. Ventec's range of laminates & prepregs include signal integrity/high-speed digital, RF/Analog & high-performance IMS material technology, and an advanced range of thermal management solutions designed for specialized use in industries including automotive, communication, aerospace, and defense. Ventec also provides value-added one-stop shop services to support PCB manufacturing and distributes a range of third-party materials and automated production equipment that complement its core product offering. Operating its own fully controlled and managed global supply chain and worldwide sales and technical support network, Ventec has manufacturing, and distribution facilities located throughout Asia, Europe, and the US, certified to AS9100 Revision D, IATF 16949:2016 and ISO 9001:2015.

For more information, visit www.venteclaminates.com

Safe Harbor Statement

This press release contains projections and other forward-looking statements regarding future events or our future financial performance. All statements other than present and historical facts and conditions contained in this release, including any statements regarding our future results of

operations and financial positions, business strategy, plans and our objectives for future operations, are forward-looking statements. These statements are only predictions and reflect our current beliefs and expectations with respect to future events and are based on assumptions and subject to risk and uncertainties and subject to change at any time. We operate in a very competitive and rapidly changing environment. New risks emerge from time to time. Given these risks and uncertainties, you should not place undue reliance on these forward-looking statements. Actual events or results may differ materially from those contained in the projections or forward-looking statements. Some of the factors that could cause actual results to differ materially from the forward-looking statements contained herein include, without limitation: (i) the contraction or lack of growth of markets in which we compete and in which our products are sold (ii) unexpected increases in our expenses, including manufacturing expenses, (iii) our inability to adjust spending quickly enough to offset any unexpected revenue shortfall, (iv) delays or cancellations in spending by our customers, (v) unexpected average selling price reductions, (vi) the significant fluctuation to which our quarterly revenue and operating results are subject, (vii) our inability to anticipate the future market demands and future needs of our customers, (viii) our inability to achieve new customer wins or for customer wins to result in shipments of our products at levels and in the timeframes we currently expect, (ix) our inability to execute on strategic alliances, (x) the impact of natural disasters on our sourcing operations and supply chain, and(xi) other factors detailed in documents we file from time to time with the Securities and Exchange Commission.

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